

Data sheet acquired from Harris Semiconductor SCHS044C – Revised September 2003

#### CMOS Low-Power Monostable/Astable Multivibrator

High Voltage Types (20-Volt Rating)

CD4047B consists of a gatable astable multivibrator with logic techniques incorporated to permit positive or negative edge-triggered monostable multivibrator action with retriggering and external counting options.

Inputs include +TRIGGER, -TRIGGER, ASTABLE, ASTABLE, RETRIGGER, and EXTERNAL RESET. Buffered outputs are  $\overline{Q}$ , Q, and OSCILLATOR. In all modes of operation, and external capacitor must be connected between C-Timing and RC-Common terminals, and an external resistor must be connected between the R-Timing and RC-Common terminals.

Astable operation is enabled by a high level on the ASTABLE input or a low level on the ASTABLE input, or both. The period of the square wave at the Q and Q Outputs in this mode of operation is a function of the external components employed. "True" input pulses on the ASTABLE input or "Complement" pulses on the ASTABLE input allow the circuit to be used as a gatable multivibrator. The OSCILLATOR output period will be half of the Q terminal output in the astable mode. However, a 50% duty cycle is not guaranteed at this output.

The CD4047B triggers in the monostable mode when a positive-going edge occurs on the +TRIGGER-input while the -TRIGGER is held low. Input pulses may be of any duration relative to the output pulse.

If retrigger capability is desired, the RETRIGGER input is pulsed. The retriggerable mode of operation is limited to positive-going edge. The CD4047B will retrigger as long as the RETRIGGER-input is high, with or without transitions (See Fig. 34).

An external countdown option can be implemented by coupling "Q" to an external "N" counter and resetting the counter with the trigger pulse. The counter output pulse is fed back to the ASTABLE input and has a duration equal to N times the period of the multivibrator.

A high level on the EXTERNAL RESET input assures no output pulse during an "ON" power condition. This input can also be activated to terminate the output pulse at any time. For monostable operation, whenever  $V_{\mbox{DD}}$  is applied, an internal power-on reset circuit will clock the Q output low within one output period ( $t_{\mbox{M}}$ ).

The CD4047B-Series types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

## CD4047B Types

#### Features:

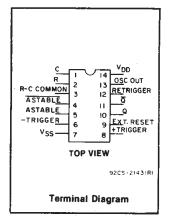
- Low power consumption: special CMOS oscillator configuration
- Monostable (one-shot) or a stable (free-running) operation
- True and complemented buffered outputs
- Only one external R and C required
- Buffered inputs
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

#### Monostable Multivibrator Features:

- Positive- or negative-edge trigger
   Output outse width independent of
- Output pulse width independent of trigger pulse duration
- Retriggerable option for pulse width expansion
- Internal power-on reset circuit
- Long pulse widths possible using small RC components by means of external counter provision
- Fast recovery time essentially independent of pulse width
- Pulse-width accuracy maintained at duty cycles approaching 100%

#### Astable Multivibrator Features:

- Free-running or gatable operating modes
- 50% duty cycle



- Oscillator output available
- Good astable frequency stability: Frequency deviation:

=  $\pm 2\% + 0.03\%$ /°C @ 100 kHz =  $\pm 0.5\% + 0.015\%$ /°C @ 10 kHz (circuits "trimmed" to frequency  $V_{DD} = 10 \text{ V} \pm 10\%$ )

#### Applications:

Digital equipment where low-power dissipation and/or high noise immunity are primary design requirements:

- **■** Envelope detection
- Frequency multiplication
- Frequency division
- Frequency discriminators
- Timing circuits
- Time-delay applications

#### **RECOMMENDED OPERATING CONDITIONS**

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIN	UNITS	
	MIN,	MAX.	UNHS
Supply-Voltage Range (For T <sub>A</sub> = Full Package-Temperature Range)	3	18	٧
NOTE: IF AT 15 V OPERATION A 10 MQ RESISTOR IS USED T TEMPERATURE SHOULD BE BETWEEN -25℃ and 10		RATING	

#### MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V <sub>DD</sub> )	
Voltages referenced to V <sub>SS</sub> Terminal)	0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	0.5V to V <sub>DD</sub> +0.5V
DC INPUT CURRENT, ANY ONE INPUT	±10mÄ
POWER DISSIPATION PER PACKAGE (PD):	
For T <sub>A</sub> = -55°C to +100°C	500mW
For $T_A = +100^{\circ}C$ to $+125^{\circ}C$	. Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package	Types)
OPERATING-TEMPERATURE RANGE (TA)	
STORAGE TEMPERATURE RANGE (Tstg)	65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 $\pm$ 1/32 inch (1.59 $\pm$ 0.79mm) from case for 10s ma	x+265°C

#### CD4047B Types

## CD4047B FUNCTIONAL TERMINAL CONNECTIONS NOTE: IN ALL CASES EXTERNAL RESISTOR BETWEEN TERMINALS 2 AND 3<sup>A</sup> EXTERNAL CAPACITOR BETWEEN TERMINALS 1 AND 3<sup>A</sup>

	TERMIN	AL CONNE	CTIONS	OUTPUT	OUTPUT PERIOD
FUNCTION	TO V <sub>DD</sub> TO V <sub>SS</sub>		INPUT TO	PULSE FROM	OR PULSE WIDTH
Astable Multivibrator:					
Free Running	4,5,6,14	7,8,9,12	_	10,11,13	$t_{\Delta}$ (10,11) = 4.40 RC
True Gating	4,6,14	7,8,9,12	5	10,11,13	t <sub>A</sub> (10,11) = 4.40 RC t <sub>A</sub> (13) = 2.20 RC#
Complement Gating	6,14	5,7,8,9,12	4	10,11,13	<b>1</b>
Monostable Multivibrator:					
Positive-Edge Trigger	4,14	5,6,7,9,12	8	10,11	1
Negative-Edge Trigger	4,8,14	5,7,9,12	6	10,11	t <sub>M</sub> (10,11) = 2.48 RC
Retriggerable	4,14	5,6,7,9	8,12	10,11	
External Countdown*	14	5,6,7,8,9,12		10,11	

- ▲ See Text.
- # First positive ½ cycle pulse-width = 2.48 RC, see Note on Page 3-134.
- \* Input Pulse to Reset of External Counting Chip External Counting Chip Output To Terminal 4

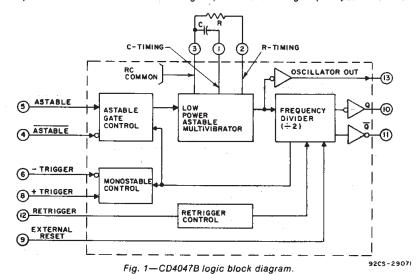


Fig. 2—CD4047B logic diagram.

#### CD4047B Types

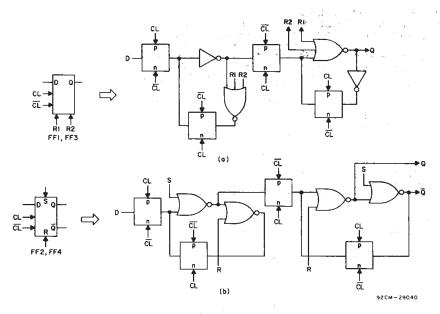


Fig. 3—Detail logic diagram for flip-flops FF1 and FF3 (a) and for flip-flops FF2 and FF4 (b).

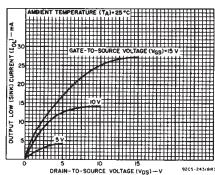


Fig. 4—Typical output low (sink) current characteristics.

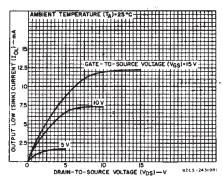


Fig. 5—Minimum output low (sink) current characteristics.

#### STATIC ELECTRICAL CHARACTERISTICS

CHARAC- TERIS-	co	NDITIO	NS	LIMIT	(°C)						
TICS	v <sub>o</sub>	VIN	VDD					<u></u>	+ 25		UNITS
	(v)	(V)	(V)	<b>-55</b>	-40	+ 85	+ 125	Min.	Тур.	Max.	
Quiescent		0,5	5	1	1	30	30	_	0.02	1	
Device Cur-	_	0,10	10	2	2	60	60	_	0.02	2	]
rent, I <sub>DD</sub>	_	0,15	15	4	4	120	120	_	0.02	4	μΑ -
Max.		0,20	20	20	20	600	600	_	0.04	20	
Output Low	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_	
(Sink)	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	_	1
Current IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8		mA
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	_	1
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	<u> </u>	]
Current,	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6		
IOH Min.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	_	]
Output Volt-		0,5	5		0.05			_	0	0.05	
age: Low-		0,10	10		0.05				0	0.05	l <sub>v</sub>
Level VOL		0,15	15		0.05				. 0	0.05	

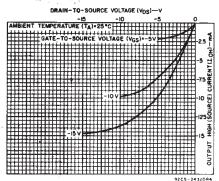


Fig. 6—Typical output high (source) current characteristics.

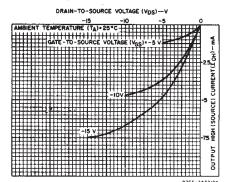


Fig. 7—Minimum output high (source) current characteristics.

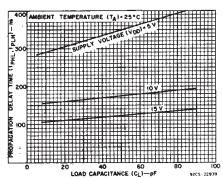


Fig. 8—Typical propagation delay time as a function of load capacitance (Astable, Astable to Q, Q).

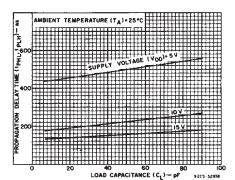


Fig. 9—Typical propagation delay time as a function of load capacitance (+ or – trigger to Q, \overline{Q}).

#### STATIC ELECTRICAL CHARACTERISTICS (CONTINUED)

CHARAC- TERIS-	CO	OITIO	NS	LIMITS AT INDICATED TEMPERATURES (°C)								
TICS	ics vo vin vDD								+ 25		UNITS	
<del>-</del>	(V)	(V)	(V)	-55	-40	+ 85	+ 125	Min.	Тур.	Max.	]	
Output Volt-		0.5	5		4.95				5			
age: High-		0,10	10		9.95			9.95	10	_	1	
Level, V <sub>OH</sub> Min.	_	0,15	15		14.	95		14.95	15	_	\ \	
Input Low	0.5,4.5		5		1.	5		_	_	1.5		
Voltage, VIL	_1,9	_	10		3			_	_	3	i I	
Max.	1.5,13.5	_	15		4			_		4	ĺν	
Input High	0.5,4.5	_	5		3.	5		3.5	_		1	
Voltage,	1.9	_	10		7			7		_	1	
V <sub>IH</sub> Min.	1.5,13.5	_	15		11			11	_		1	
Input Cur- rent I <sub>IN</sub> Max.	_	0,18	18	± 0.1					± 10 <sup>5</sup>	±0.1	μΑ	

#### DYNAMIC ELECTRICAL CHARACTERISTICS at TA = 25°C; Input t,t, = 20 ns,

#### $C_{L} = 50 pF, R_{L} = 200 k\Omega$

CHARACTERISTIC	V <sub>DD</sub> (V)		LIMITS		UNITS
O'IANAO I ENIOTIC	*0D (*)	MIN.	TYP.	MAX.	UNITS
Propagation Delay Time, tehl, telh	5		200	400	
Astable, Astable to Osc. Out	10	_	100	200	
	15	-	80	160	1
	5	_	350	700	1
Astable, Astable to Q, Q	10	_	. 175	350	
	15	_	125	250	
	5		500	1000	1
+ or - Trigger to Q, Q	10	-	225	450	
	15	-	150	300	
	5		300	600	1
Retrigger to Q, Q	10	_	150	300	1
	15	_	100	200	
	5		250	500	1
External Reset to Q, Q	10	-	100	200	กร
	15	l –	70	140	1
Transition Time, t <sub>THL</sub> , t <sub>TLH</sub>	5		100	200	1
Osc. Out, Q, Q	10	<b> </b>	50	100	
•	15	-	40	80	
Minimum Input Pulse	5	_	200	400	1
Width, tw	10	_	80	160	1
+ Trigger, - Trigger	15	-	50	100	
	5	_	100	200	1
Reset	10	_	50	100	
	15	–	30	60	
	5	_	300	600	1
Retrigger	10	_	115	230	
	15	-	75	150	
Input Rise and Fall Time, tr,tr					<del>                                     </del>
All Trigger Inputs	1				
For + Trigger: t <sub>f</sub>	5	-	270	-	1
t <sub>r</sub> only is unlimited	10	–	18	-	
	15	l –	9	-	μs
For - Trigger: t.	5		325	_	1
t <sub>f</sub> only is unlimited	10		9	l –	1
	15	_	4	_	
Q or Q Deviation from 50%	5		±0.5	±1	
Duty Factor	10	-	±0.5	±1	%
	15	_	±0.1	±0.5	
Input Capacitance, CIN	Any Input		5	7.7	pF

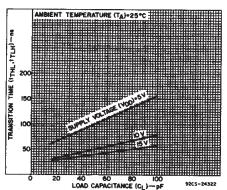


Fig. 10—Typical transition time as a function of load capacitance.

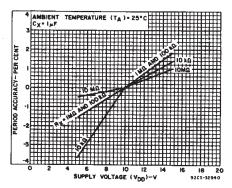


Fig. 11—Typical astable oscillator or Q,  $\overline{Q}$  period accuracy vs. supply voltage.

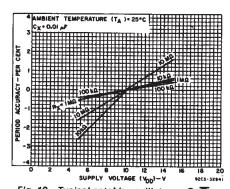


Fig. 12—Typical astable oscillator or Q, Q period accuracy vs. supply voltage.

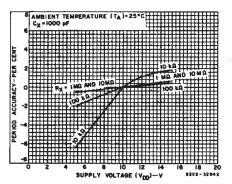


Fig. 13—Typical astable oscillator or Q,  $\overline{Q}$  period accuracy vs. supply voltage.

#### CD4047B Types

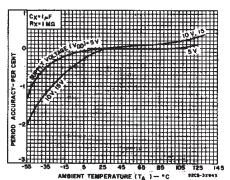


Fig. 14—Typical astable oscillator or Q, Q period accuracy vs. ambient temperature (ultra-low frequency).

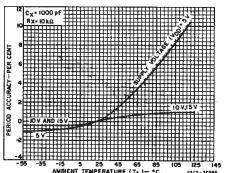


Fig. 17—Typical astable oscillator or Q, Q period accuracy vs. ambient temperature (high-frequency).

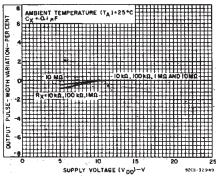


Fig. 20—Typical output pulse-width variations vs. supply voltage.

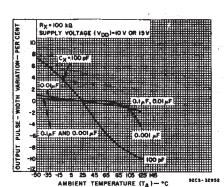


Fig. 23—Typical output pulse-width variations vs. ambient temperature.

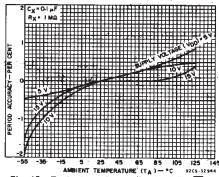


Fig. 15—Typical astable oscillator or Q, Q period accuracy vs. ambient temperature (low frequency).

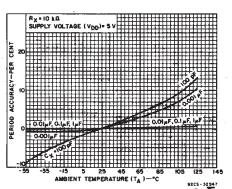


Fig. 18—Typical astable oscillator or Q, Q period accuracy vs. ambient temperature.

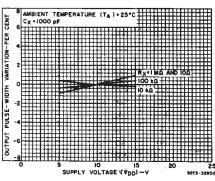


Fig. 21—Typical output pulse-width variations vs. supply voltage.

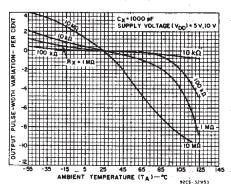


Fig. 24—Typical output-pulse-width variations vs. ambient temperature.

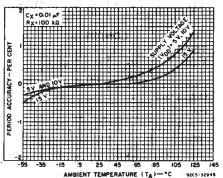


Fig. 16—Typical astable oscillator or Q, Q period accuracy vs. ambient temperature (medium frequency).

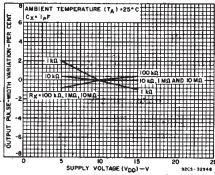


Fig. 19—Typical output pulse-width variations vs. supply voltage.

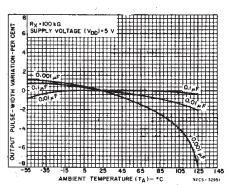


Fig. 22—Typical output pulse-width variations vs. ambient temperature.

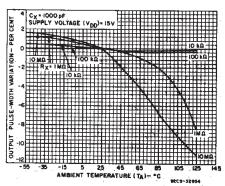


Fig. 25—Typical output pulse-width variations vs. ambient temperature.

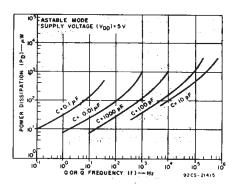


Fig. 26-Typical power dissipation vs. output frequency ( $V_{DD} = 5 V$ ).

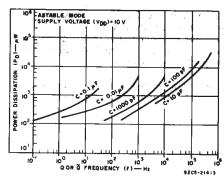


Fig. 27—Typical power dissipation vs. output frequency ( $V_{DD} = 10 \text{ V}$ ).

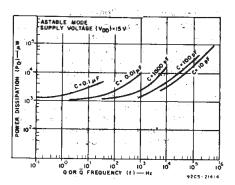


Fig. 28—Typical power dissipation vs. output frequency ( $V_{DD} = 15 \text{ V}$ ).

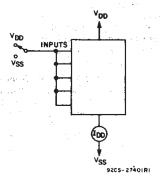


Fig. 29-Quiescent device current test circuit.

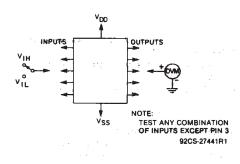


Fig. 30-Input-voltage test circuit.

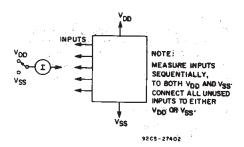


Fig. 31—Input-leakage-current test circuit

#### 1. Astable Mode Design Information

#### A. Unit-to-Unit Transfer-Voltage Variations - The following analysis presents variations from unit to unit as a function of transfer-voltage ( $V_{TR}$ ) shift (33% -67% $V_{DD}$ ) for free-running (astable) operation.



$$t_1 = -RC \ln \frac{v_{TR}}{v_{DD} + v_{TR}};$$
 
$$typically , t_1 = 1.1 RC$$

$$t_2 = -RC \ln \frac{V_{DD} - V_{TR}}{2V_{DD} - V_{TR}};$$

$$typically, t_2 = 1.1 RC$$

$$t_A = 2(t_1 + t_2)$$

$$= -2 RC \ln \frac{(V_{TR})(V_{DD} - V_{TR})}{(V_{DD} + V_{TR})(2V_{DD} - V_{TR})}$$

thus if  $t_A=4.40\,\mathrm{RC}$  is used, the variation will be +5%, -0% due to variations in transfer voltage.

B. Variations Due to V<sub>DD</sub> and Temperature Changes — In addition to variations from unit to unit, the astable period varies with V<sub>DD</sub> and temperature. Typical variations are presented in graphical form in Figs. 11 to 16 with 1037 as reference for voltage variations curves and 25°C as reference for temperature variations curves.

#### II. Menostable Mode Design Information The following analysis presents variations from unit to unit as a function of transfer-voltage (VTR) shift (33% - 67% V<sub>DD</sub>) for one-shot (monostable) operation.

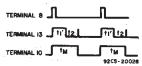
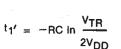


Fig. 33-Monostable waveforms.



typically, t<sub>1</sub>' = 1.38 RC

$$t_{M} = (t_{1}r_{+} t_{2})$$

$$t_{M} = -RC \ln \frac{(V_{TR})(V_{DD} - V_{TR})}{(2V_{DD} - V_{TR})(2V_{DD})}$$

where  $t_{M}=$  Monostable mode pulse width. Values for  $t_{M}$  are as follows:

Typ:  $V_{TR} = 0.5 V_{DD}$  $t_{M} = 2.48 RC$ Min:  $V_{TR} = 0.33 V_{DD}$ t<sub>M</sub> = 2.71 RC t<sub>M</sub> = 2.48 RC Max:  $V_{TR} = 0.67 V_{DD}$ 

thus is  $t_{M}=2.48\,RC$  is used, the variation will be  $+9.3\%,\;-0\%$  due to variations in transfer voltage.

In the astable mode, the first positive half cycle has a duration of t<sub>M</sub>; succeeding durations are t<sub>A</sub>/2.

In addition to variations from unit to unit, the monostable pulse width varies with V<sub>DD</sub> and temperature. These variations are presented in graphical form in Fig. 19 to 26 with 10 V as reference for voltagevariation curves and 25°C as reference for temperature-variation curves.

#### III. Retrigger Mode Operation

The CD4047B can be used in the retrigger mode to extend the output-pulse duration, or to compare the frequency of an input signal with that of the internal oscillator. In the retrigger mode the input pulse is applied to terminal 12, and the output is taken from terminal 10 or 11. As shown in Fig. 34 normal monostable action is obtained when one retrigger pulse is applied. Extended pulse duration is obtained when more than one pulse is applied.

larger than the CMOS "ON" resistance in series with it, which typically is hundreds of ohms. In addition, with very large values of R, some short-term instability with respect to time may be noted.

The recommended values for these components to maintain agreement with

tion of leakage current in the circuit, as shown in the static electrical characteristics. For dynamic operation, the power needed to charge the external timing capacitor C is given by the following formulae:



 $P = 2CV^2f$ . (Output at terminal No. 13)  $P = 4CV^2f$ . (Output at terminal Nos. 10 and 11)

#### Monostable Mode:

$$P = \frac{(2.9CV^2) \text{ (Duty Cycle)}}{T}$$

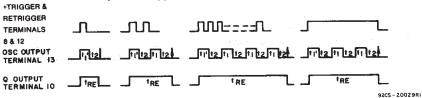


Fig. 34-Retrigger-mode waveforms.

For two input pulses,  $t_{RE}=t_1^\prime+t_1+2t_2$ . For more than two pulses, the output pulse width is an integral number of time periods, with the first time period being  $t_1^\prime+t_2$ , typically, 2.48RC, and all subsequent time periods being  $t_1+t_2$ , typically, 2.2RC.

#### **IV. External Counter Option**

Time  $t_{\mbox{\scriptsize M}}$  can be extended by any amount with the use of external counting cir-

cuitry. Advantages include digitally controlled pulse duration, small timing capacitors for long time periods, and extremely fast recovery time. A typical implementation is shown in Fig. 35. The pulse duration at the output is

$$t_{ext} = (N - 1)(t_A) + (t_M + t_A/2)$$

where  $t_{\text{ext}}$  = pulse duration of the circuitry, and N is the number of counts used.

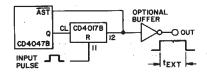


Fig. 35—Implementation of external counter option.

9208-2904

#### V. Timing-Component Limitations

The capacitor used in the circuit should be non-polarized and have low leakage (i.e. the parallel resistance of the capacitor should be at least an order of magnitude greater than the external resistor used). There is no upper or lower limit for either R or C value to maintain oscillation.

However, in consideration of accuracy, C must be much larger than the inherent stray capacitance in the system (unless this capacitance can be measured and taken into account). R must be much

previously calculated formulas without trimming should be:

C ≥ 100 pF, up to any practical value, for astable modes;

 $C \ge 1000 \text{ pF}$ , up to any practical value for monostable modes.

10 kQ ≤ R ≤ 1 MQ

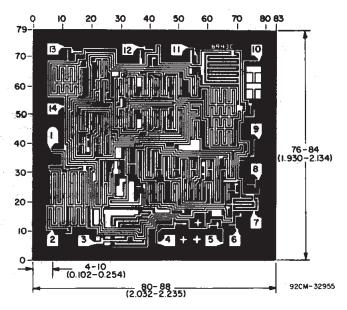
#### VI. Power Consumption

in the standby mode (Monostable or Astable), power dissipation will be a func-

(Output at terminal Nos. 10 and 11)

The circuit is designed so that most of the total power is consumed in the external components. In practice, the lower the values of frequency and voltage used, the closer the actual power dissipation will be to the calculated value.

Because the power dissipation does not depend on R, a design for minimum power dissipation would be a small value of C. The value of R would depend on the desired period (within the limitations discussed above). See Figs. 27, 28, and 29 for typical power consumption in astable mode.



Chip dimensions and pad layout for CD4047B

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10<sup>-3</sup> inch).

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#### **PACKAGING INFORMATION**

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
8102001CA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8102001CA CD4047BF3A
CD4047BD3	Active	Production	CDIP SB (JD)   14	24   TUBE	No	AU	N/A for Pkg Type	-55 to 125	CD4047BD/3
CD4047BD3.A	Active	Production	CDIP SB (JD)   14	24   TUBE	No	AU	N/A for Pkg Type	-55 to 125	CD4047BD/3
CD4047BE	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4047BE
CD4047BE.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4047BE
CD4047BEE4	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4047BE
CD4047BF	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4047BF
CD4047BF.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4047BF
CD4047BF3A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8102001CA CD4047BF3A
CD4047BF3A.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8102001CA CD4047BF3A
CD4047BM	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-55 to 125	CD4047BM
CD4047BM96	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4047BM
CD4047BM96.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4047BM
CD4047BM96G4	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4047BM
CD4047BMT	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-55 to 125	CD4047BM
CD4047BNSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4047B
CD4047BNSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4047B
CD4047BPW	Obsolete	Production	TSSOP (PW)   14	-	-	Call TI	Call TI	-55 to 125	CM047B
CD4047BPWR	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM047B
CD4047BPWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM047B

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

#### **PACKAGE OPTION ADDENDUM**

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(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF CD4047B, CD4047B-MIL:

Catalog: CD4047B

Military: CD4047B-MIL

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

Military - QML certified for Military and Defense Applications

#### **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION



# TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

	· · · · · · · · · · · · · · · · · · ·
A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4047BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4047BNSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4047BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4047BM96	SOIC	D	14	2500	356.0	356.0	35.0
CD4047BNSR	SOP	NS	14	2000	356.0	356.0	35.0
CD4047BPWR	TSSOP	PW	14	2000	356.0	356.0	35.0

#### **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4047BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4047BE.A	N	PDIP	14	25	506	13.97	11230	4.32
CD4047BEE4	N	PDIP	14	25	506	13.97	11230	4.32

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



#### N (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



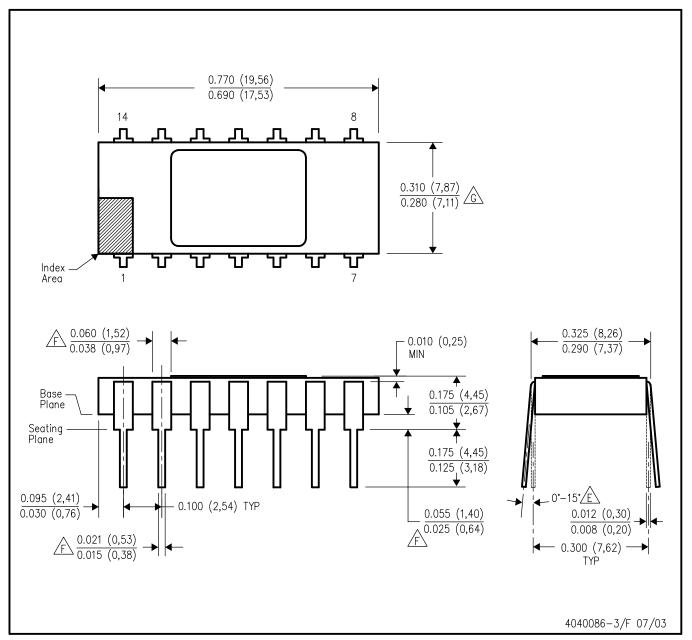
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### JD (R-CDIP-T14)

#### CERAMIC SIDE-BRAZE DUAL-IN-LINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Controlling dimension: inch.
- D. Leads within 0.005 (0,13) radius of true position (TP) at gage plane with maximum material condition and unit installed.
- E Angle applies to spread leads prior to installation.
- F Outlines on which the seating plane is coincident with the plane (standoff = 0), terminals lead standoffs are not required, and lead shoulder may equal lead width along any part of the lead above the seating/base plane.
- G Body width does not include particles of packing materials.
- H. A visual index feature must be located within the cross—hatched area.





SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### **MECHANICAL DATA**

#### NS (R-PDSO-G\*\*)

### 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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